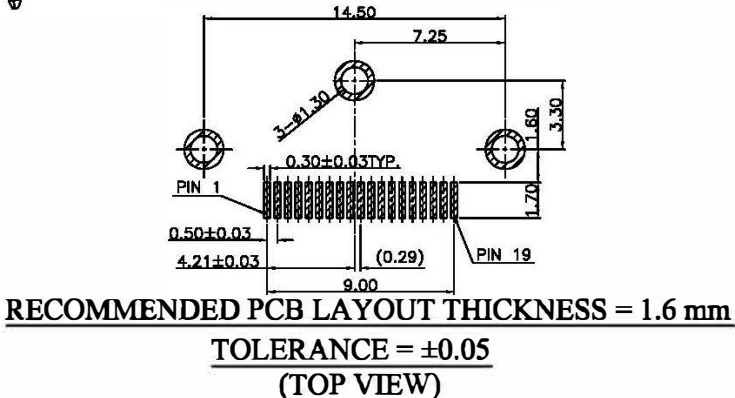


- NOTES:
- MATERIAL:
    - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL 94V-0 RATED, BLACK
    - CONTACT: COPPER ALLOY
    - SHELL: COPPER ALLOY/SPCC
  - PLATING:
    - CONTACT: GOLD PLATED OVER NICKEL
    - SHELL: NICKEL PLATED
  - P/N: HHF-33X000-XSB
- TERMINAL PLATING CODE: REV. CODE
- A: CONTACT AREA: GOLD FLASH  
 SOLDER AREA: MATTE TIN 100u"  
 B: CONTACT AREA: 3u" GOLD  
 SOLDER AREA: MATTE TIN 100u"  
 C: CONTACT AREA: 15u" GOLD  
 SOLDER AREA: MATTE TIN 100u"



A	新版发行	chu	2010-12-05
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期

MATERIAL	TOLERANCE UNSPECIFIED	ALL LINK CONN. TECHNOLOGY CORP.	
	0.0 ±0.30 0' ±2' 0.00±0.20 0' ±1' 0.000±0.10 0' ±0.5'	SCALE 1:1	UNIT mm
FINISH	DRAWN 孙洪桥 09/05/25	NAME	
	DESIGNER 孙洪桥 09/05/25	IDMI A/F 朝天式 SMT TYPE	
	CHECKED	DRAWING NO. HHF-33X000-XSB	
APPROVED			REV A